

## West Bond Model 454647E-79 Semi-automatic Wire Bonder



Wire bonder makes interconnections between an integrated circuit (IC) or other semiconductor device and its packaging during semiconductor device fabrication. It is used to assemble the vast majority of semiconductor packages.

### Specifications

- *CONTROL LOGIC: Motorola 68000 microprocessor*
- *TOOL Z STROKE: 0.5 inch*
- *TOOL Y STROKE: 0.5 inch*
- *MANUAL Z ENCODER RESOLUTION: 0.001 inch*
- *FORCE RANGE: Adjustable, 10-250 grams,*
- *BOND FORCE: High / Low Programmable*
- *ULTRASONICS: Built-in, 8 bit, 5 watts*
- *ANGLED FEED TOOL LENGTH: 0.750 inch*
- *VERTICAL FEED TOOL LENGTH: 0.750 inch*
- *BALL CAPILLARY LENGTH: 0.625 inch*
- *WIRE RANGE: 0.7 to 2 mils, ½ x10 mil gold ribbon (vertical feed)*
- *WIRE SPOOL MOUNT: 0.5 inch with ball bearing roller*
- *RADIANT TOOL HEAT: Built-in*
- *DIMENSION: W=24.218" x D=22.297" x H=11.000"*
- *WEIGHT: 75 lbs uncreated, or 110 lbs accessorized and created*